

protuberances project above the average adhesive height on the chip 20, such protuberances become pressure focal points that receive the most abrasion or cutting. Fig. 1C shows the chip 20 after the bumps have been exposed via abrasion. Once the bumps have been exposed, a film, tape or other type of protective cover may be applied to the chip 20 to protect the adhesive 26 and the exposed humps 24.

A version marked to show changes made to the specification relative to the previous version of the specification is attached.